



Materials Declaration

Package	LQFP
Body Size	20 X 20
LeadCount	184
Option	Pb Free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	5.53 E-02	40613
SiO2 Filler	86	5.95 E-01	436590
Phenol Resin	5	3.46 E-02	25383
Antimony_Sb2O3	0.4	2.77 E-03	2031
Brominated Resin	0.4	2.77 E-03	2031
Carbon Black	0.2	1.38 E-03	1015
Sub-Total		6.92 E-01	507662

Molding Compound		
Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	5.53 E-01	406026
Ni	3	1.73 E-02	12662
Si	0.65	3.74 E-03	2743
Mg	0.15	8.63 E-04	633
Sub-Total		5.75 E-01	422065

Die Attach Paste		
Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Internal Leadframe Plating			
	% of Plating	Weight (g)	PPM
Ag	100	3.50 E-03	2569

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100	7.14 E-02	52372
Sub-Total		7.14 E-02	52372

Bond Wires			
	% of Wire	Weight (g)	PPM
Au	99.99	8.85 E-04	649

Chip			
	% of Chip	Weight (g)	PPM
Si	100	7.04 E-04	517

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Resin	26	5.02 E-03	3683
Ag Filler	74	1.43 E-02	10483
Sub-Total		1.93 E-02	14166

Package Totals	
Weight (g)	PPM
1.36 E+00	1000000

STS-ST-C

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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7/7/05





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Si	0.65	3.74 E-03	2743
Mg	0.15	8.63 E-04	633
Sub-Total		5.75 E-01	422065

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100	3.50 E-03	2569

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	85	6.08 E-02	44516
Pb	15	1.07 E-02	7856
Sub-Total		7.14 E-02	52372

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	8.85 E-04	649

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100	7.04 E-04	517

Die Attach			
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Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

STS-ST-A

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